

ABSTRACT

The present invention relates to a cover tape for tape packaging electronic components that heat-seals a carrier tape accommodating therein electronic components. A cover tape
5 for tape packaging electronic components according to the present invention includes a substrate film layer, a soft material layer, and a thermal adhesive layer. The soft material layer is formed of metallocene linear low-density polyethylene having a specific gravity in a range of from 0.888 to 0.907.